Bencent®

BGO6000A10-LC2

Order Code: BGO6000A10-LC2

Bencent Composite Product

Version: A1 2018-10-22

Features

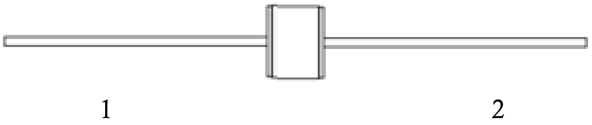
- High Current Handling Capability 10,000A @ 8/20μ s
- Low Capacitance and Insertion Loss
- Fast Response and Long Service Life
- Reliable to Protect Electrostatic Surge
- Moisture sensitivity level：Level 1
- Current Limiting, available 1-30A @680VAC

Exterior

Application Information

- AC Power

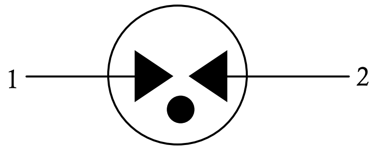
Package (Top View)



Agency Approvals

Icon	Description
RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003
Pb	Mean lead free
UR	Compliance with UL1449, Certificated E337906

Schematic Symbol



Electrical Parameter

DC Breakdown Voltage1) 2)	100V/s	>480	V
Impulse Spark-over Voltage	at 1kV/μs	for 99 % of measured values ≤1500	V
Impulse Discharge Current3)	8/20μs ±10times	10	KA
Arc Voltage	at 1A	~40	V
Insulation Resistance	DC=100V	≥1	GΩ
Capacitance at 1 MHz	V_{DC}=0.5V	≤1.5	pF
Weight		~1.62	g
Operating and storage Temperature		-40-125	℃
Marking		Bencent Logo 600	

1) At delivery AQL 0.65 level II ISO 2859
2) In ionized mode
3) Terms and current waveforms in accordance with ITU-T Rec. K. 12; IEC 61643-21

Open Characteristic

Voltage Rating(V)	680	680	680	680	680	680
Short Circuit Current Ampera Rating(A)	1.2	2	6	12	24	30
Open Time(S) Max.	30	15	8	5	5	3

Note: Heat shrinkable tube and encapsulating are not recommended to use on the surface of BGO product.
The tolerance of open Ampera Rating and Voltage Rating is ±5%.

Part Numbering System

BGO	6000	A10	-L	C	2
(1)	(2)	(3)	(4)	(5)	(6)

(1)Bencent Open GDT
(2)Rated DC Breakdown Voltage, 6000:600*10^0=600V
(3)Surge Rating, A10: 8/20μs 10KA
(4)Structure, L: Axial Lead
(5)Dimension, C: Φ8×7mm
(6)Pin Number, 2pin

Product Characteristics

Lead Material	Copper&Irio-nickel
Body Material	Ceramics Iron-nickelelectrode
Terminal Finish	100% Matte-Tin Plated

Environmental Reliability Characteristics

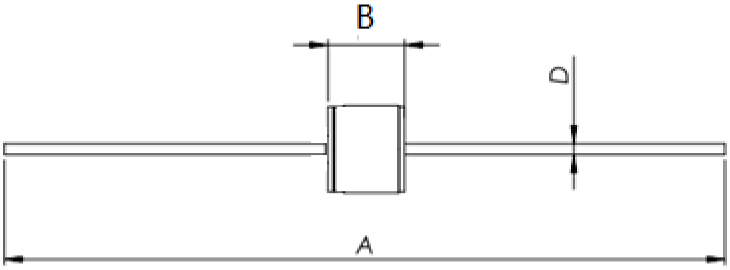
Testing items	**Technical standards**
High Temperature Storage Test	Temperature: 125℃ Time:2H
Low Temperature Storage Test	Temperature: -40℃ Time:2H
Thermal Shock	Temperature:-40-125℃ Cycle:50
Vibration	Frequency：10-500Hz Amplitude：0.15mm Time：45mins
Resistance of soldering heat	Temperature: 260±5℃ Time of dip soldering：10s，1time

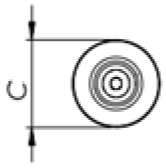
Note: Up-screen program can be specified by customer's request via contacting Bencent service

Solderability Test

Solderability	Solder Pot Temperature:	245℃ ±5℃
	Solder Dwell Time:	4-6 seconds

Product Dimensions

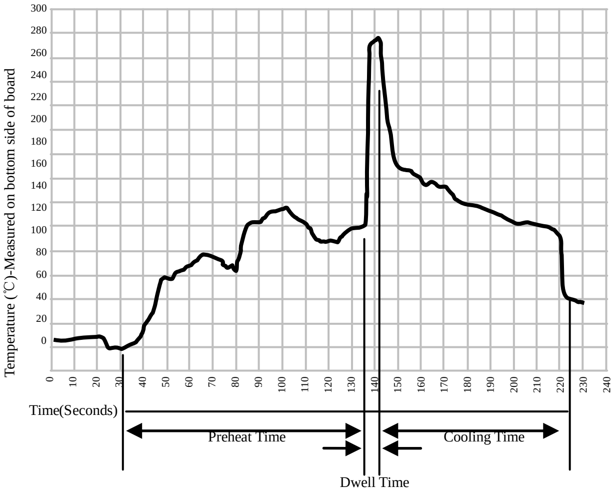




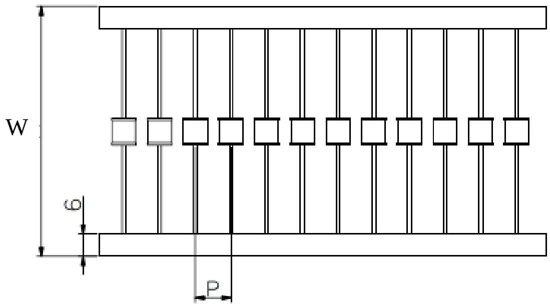
REF	**Mm**	**inch**
A	62±2	2.441±0.079
B	7±1.4	0.276±0.024
C	Φ8±0.5	Φ0.390±0.020
D	Φ0.8±0.1	Φ0.039±0.004

Wave Soldering Profile

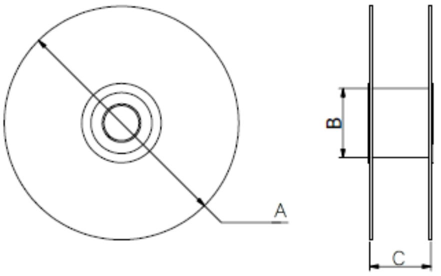
Wave Soldering Condition		**Pb-Free assembly**
Pre Heat	Temperature Min	100°C
	Temperature Max	150°C
	Time （min to max）	60 – 180 secs
Solder Pot Temperature		270℃ Max
Solder Dwell Time		2-5 seconds



Package Reel Information



REF	**mm**	**inch**
W	65±3	2.559±0.118
P	10±1	0.394±0.039
A	Φ340±2	Φ13.386±0.079
B	Φ83±2	Φ3.268±0.079
C	73±3	2.874±0.118



OUTLINE	REEL (PCS)	PER CARTON (PCS)	CARTON SIZE(mm)		
			L	W	H
TAPING	700	4200	480	350	360